



Samsung's 3D V-NAND (page 16)



**DEPARTMENTS**

	AEI NEWS	8
	IN VIEW THIS MONTH	12
	BUSINESS STRATEGY	54
	PRODUCT NEWS	66

ASIA ELECTRONICS INDUSTRY (ISSN 1342-422X) is published monthly by Dempa Publications, Inc., 1-11-15 Higashi Gotanda, Shinagawa-ku, Tokyo 141-8715, Japan Tel: +81-3-3445-6111 Fax: +81-3-3447-4666. Editorial e-mail: may@dempa.co.jp; Subscription e-mail: circmnl@pltdsl.net. The magazine is distributed free to qualified subscribers in ASEAN countries (Thailand, Indonesia, The Philippines, Malaysia, Singapore, Brunei, Vietnam, Myanmar, Cambodia and Laos), as well as Korea, Taiwan and Hong Kong.

Paid air mail subscription is available to non-qualified subscribers in the Asian and Pacific regions for US\$150 per year and US\$260 for two years. For other areas, air mail subscription fees are US\$160 per year and US\$280 for two years. Paid subscription is accepted at <http://aei.dempa.net/paidsub/subscription.html>

Send address corrections to Dempa Publications, Inc., c/o Quantum Solutions (HK) Ltd, Unit 3-6, G/F Pacific Trade Centre, 2 Kai Hing Road, Kowloon Bay, Kowloon, Hong Kong

**Taiwan:** International Dempa Trade Co., Ltd., 7F-1, No. 36, Nanking W. Rd., Taipei, Taiwan, Tel: +886-2-2558-1817 Fax: +886-2-2555-6428  
**Korea:** Dempa Publications, Seoul Office, Masters Tower, Room 1404, 553 Dohwa-dong, Mapo-ku, Seoul, Korea, 121-040, Tel: +82-2-714-2983 Fax: +82-2-714-2984  
**Philippines:** Dempa Publications, Inc. - Regional Headquarters, Herrera Tower, Room 2510, 98 V.A. Rufino Street, Salcedo Village, Makati City, Philippines, Tel: +63-2-845-0906 Fax: +63-2-845-1829

President & Publisher: Tetsuo Hirayama  
 Copyright © 2017 by Dempa Publications, Inc.

All rights reserved. The contents of this magazine may not be reproduced in whole or in part without the prior permission of the copyright owner. Printed in Hong Kong.

**INDUSTRY REPORT**

Electronic Component Firms Deal with Challenges to Assure Growth \_\_\_\_\_ 10

**IN FOCUS**

Lasertec's Solutions Improve Wafer Edge Yield \_\_\_\_\_ 14

**SPECIAL REPORT**

All-Flash Servers Bring Back Glory Days of Chip Equipment \_\_\_\_\_ 16

Big Data, Servers to Propel Semiconductor Market Tailwind \_\_\_\_\_ 20

Unique Technologies Yield Cutting-Edge Solder Products \_\_\_\_\_ 23

In Digital World, Drones Emerge as Service Tool \_\_\_\_\_ 27

Reliable Chip Components Rise up to Latest Modules, Devices \_\_\_\_\_ 29

Mounters Flex Muscle to Meet Diverse Production Needs \_\_\_\_\_ 32

**TECHNOLOGY FOCUS**

Plasma Technologies Ease Wafer Manufacturing of IoT Devices \_\_\_\_\_ 33

Compact Multi-Sensor Module Jumpstarts IoT, Wearables \_\_\_\_\_ 36

Linear Resistors Keep Stability in Wide Temperature Range \_\_\_\_\_ 37

Use of Carbon Nanotube Extends Beyond EDLC Sheets \_\_\_\_\_ 40

**TECHNOLOGY HIGHLIGHT**

Fin-Shaped MONOS Flash Memory Cells Ready for Finer Process Nodes \_\_\_\_\_ 42

Transistor-Powered LSI Promotes Ultralow Energy Use \_\_\_\_\_ 44

**PRODUCT HIGHLIGHT**

Circuit Board Material Levels up Resistance for In-Car Use \_\_\_\_\_ 45

Three-Axis Floating Optical Interface Connector Simplifies Connection \_\_\_\_\_ 46

Nippon Mektron Steps up FPCs for Automotive Use \_\_\_\_\_ 47

ROHM's Chipsets Magnify In-Car LCD Panels, Foster Safety \_\_\_\_\_ 48

**SMTs: IN REVIEW**

\_\_\_\_\_ 49

**COMPONENT MATERIALS**

\_\_\_\_\_ 51

**ZOOM-IN**

Electronics Parts Makers Reinforce Business for Automotive Electronics \_\_\_\_\_ 56

**SHOW REPORT**

CES 2017 \_\_\_\_\_ 58

SEMICON Japan 2016 \_\_\_\_\_ 62

IDW/Asia Display 2016 \_\_\_\_\_ 64